

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

**TC74ACT540P, TC74ACT540F, TC74ACT540FW, TC74ACT540FT**  
**TC74ACT541P, TC74ACT541F, TC74ACT541FW, TC74ACT541FT**

**OCTAL BUS BUFFER**  
**TC74ACT540P/F/FW/FT INVERTING, 3-STATE OUTPUTS**  
**TC74ACT541P/F/FW/FT NON-INVERTING, 3-STATE OUTPUTS**

(Note) The JEDEC SOP (FW) is not available in Japan.

The TC74ACT540 / TC74ACT541 are advanced high speed CMOS OCTAL BUS BUFFERs fabricated with silicon gate and double-layer metal wiring C<sup>2</sup>MOS technology.

They achieve the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

These devices may be used as a level converter for interfacing TTL or NMOS to High Speed CMOS. The inputs are compatible with TTL, NMOS and CMOS output voltage levels.

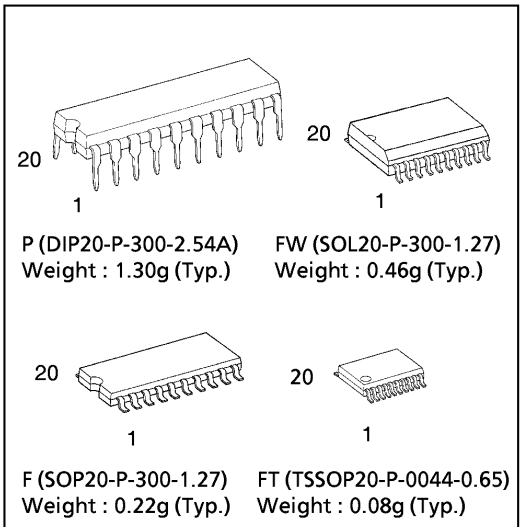
The TC74ACT540 is an inverting type, and the TC74ACT541 is a non-inverting type.

When either  $\bar{G}1$  or  $\bar{G}2$  are high, the terminal outputs are in the high-impedance state.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

**FEATURES:**

- High Speed..... $t_{pd} = 4.3ns$  (typ.) at  $V_{CC} = 5V$
- Low Power Dissipation..... $I_{CC} = 8\mu A$ (Max.) at  $T_a = 25^\circ C$
- Compatible with TTL outputs ...  $V_{IL} = 0.8V$  (Max.)  
 $V_{IH} = 2.0V$  (Min.)
- Symmetrical Output Impedance...  $|I_{OH}| = I_{OL} = 24mA$  (Min.)  
 Capability of driving  $50\Omega$  transmission lines.
- Balanced Propagation Delays.....  $t_{pLH} \approx t_{pHL}$
- Pin and Function Compatible with 74F540/541

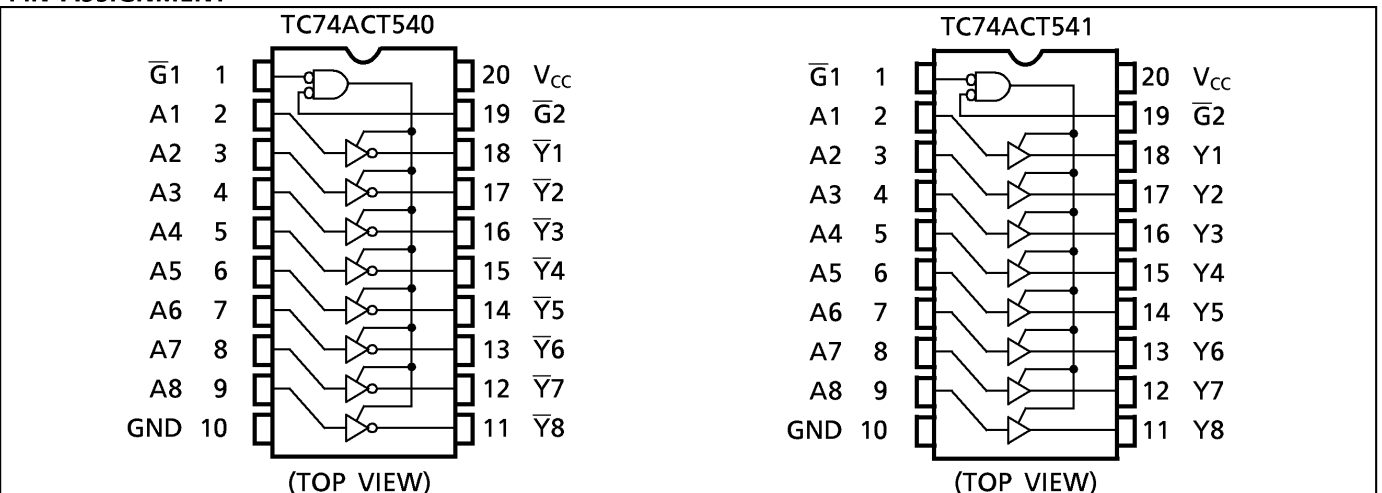


**TRUTH TABLE**

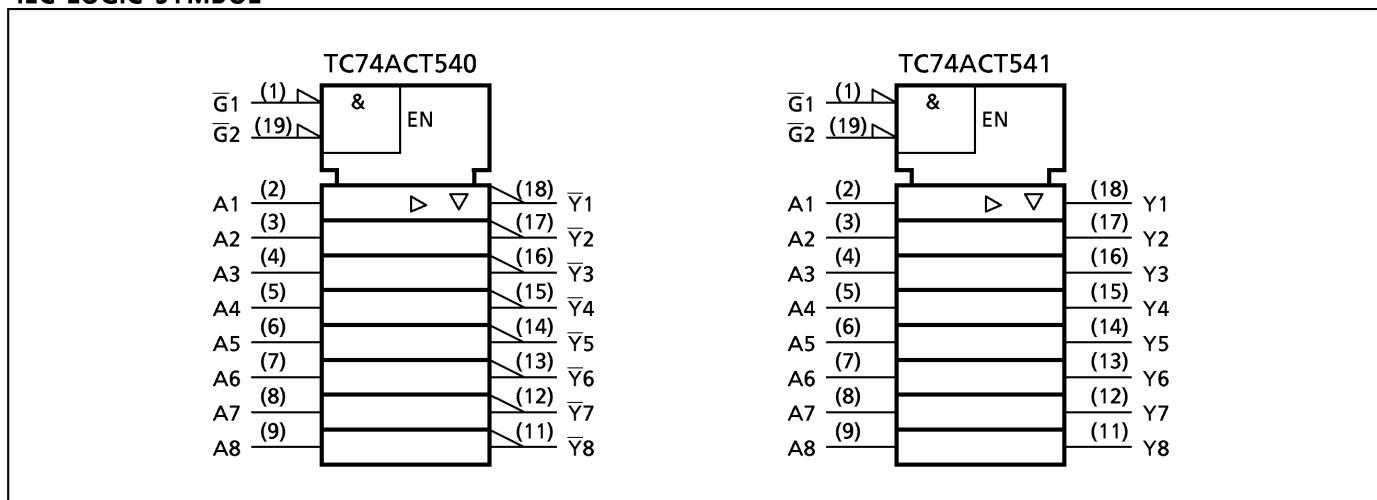
INPUTS			OUTPUTS	
$\bar{G}1$	$\bar{G}2$	$A_n$	$Y_n^*$	$\bar{Y}_n^*$
H	X	X	Z	Z
X	H	X	Z	Z
L	L	H	H	L
L	L	L	L	H

X : Don't Care  
 Z : High Impedance  
 \* :  $Y_n$  ..... ACT541  
 $\bar{Y}_n$  ..... ACT540

**PIN ASSIGNMENT**



**IEC LOGIC SYMBOL**



**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	-0.5~7.0	V
DC Input Voltage	$V_{IN}$	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	$V_{OUT}$	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	$I_{IK}$	± 20	mA
Output Diode Current	$I_{OK}$	± 50	mA
DC Output Current	$I_{OUT}$	± 50	mA
DC $V_{CC}$ /Ground Current	$I_{CC}$	± 200	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	$T_{stg}$	-65~150	°C

\*500mW in the range of  $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$ . From  $T_a = 65^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  a derating factor of  $-10\text{mW}/^{\circ}\text{C}$  should be applied up to 300mW.

**RECOMMENDED OPERATING CONDITIONS**

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	4.5~5.5	V
Input Voltage	$V_{IN}$	0~ $V_{CC}$	V
Output Voltage	$V_{OUT}$	0~ $V_{CC}$	V
Operating Temperature	$T_{opr}$	-40~85	°C
Input Rise and Fall Time	$dt/dV$	0~10	ns/V

**DC ELECTRICAL CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	V <sub>CC</sub> (V)	Ta = 25°C			Ta = -40~85°C		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
High - Level Input Voltage	V <sub>IH</sub>		4.5 } 5.5	2.0	—	—	2.0	—	V	
Low - Level Input Voltage	V <sub>IL</sub>		4.5 } 5.5	—	—	0.8	—	0.8	V	
High - Level Output Voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50μA	4.5	4.4	4.5	—	4.4	—	V
			I <sub>OH</sub> = -24mA	4.5	3.94	—	—	3.80	—	
			I <sub>OH</sub> = -75mA*	5.5	—	—	—	3.85	—	
Low - Level Output Voltage	V <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50μA	4.5	—	0.0	0.1	—	0.1	V
			I <sub>OL</sub> = 24mA	4.5	—	—	0.36	—	0.44	
			I <sub>OL</sub> = 75mA*	5.5	—	—	—	—	1.65	
3 - State Output Off - State Current	I <sub>OZ</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> V <sub>OUT</sub> = V <sub>CC</sub> or GND	5.5	—	—	±0.5	—	±5.0	μA	
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	±0.1	—	±1.0		
Quiescent Supply Current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	8.0	—	80.0	mA	
	I <sub>C</sub>	PER INPUT : V <sub>IN</sub> = 3.4V OTHER INPUT : V <sub>CC</sub> or GND	5.5	—	—	1.35	—	1.5		

\* : This spec indicates the capability of driving 50Ω transmission lines.  
One output should be tested at a time for a 10ms maximum duration.

**AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50pF, R<sub>L</sub> = 500Ω, Input t<sub>r</sub> = t<sub>f</sub> = 3ns)**

PARAMETER	SYMBOL	TEST CONDITION	V <sub>CC</sub> (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
Propagation Delay Time *	t <sub>pLH</sub>		5.0 ± 0.5	—	5.0	8.3	1.0	9.5	ns
	t <sub>pHL</sub>		5.0 ± 0.5	—	5.0	8.3	1.0	9.5	
Propagation Delay Time**	t <sub>pLH</sub>		5.0 ± 0.5	—	5.0	8.3	1.0	9.5	
	t <sub>pHL</sub>		5.0 ± 0.5	—	5.0	8.3	1.0	9.5	
Output Enable Time	t <sub>pZL</sub>		5.0 ± 0.5	—	7.3	11.4	1.0	13.0	pF
	t <sub>pZH</sub>		5.0 ± 0.5	—	7.3	11.4	1.0	13.0	
Output Disable Time	t <sub>pLZ</sub>		5.0 ± 0.5	—	5.9	9.2	1.0	10.5	pF
	t <sub>pHZ</sub>		5.0 ± 0.5	—	5.9	9.2	1.0	10.5	
Input Capacitance	C <sub>IN</sub>			—	5	10	—	10	pF
Output Capacitance	C <sub>OUT</sub>			—	10	—	—	—	
Power Dissipation Capacitance	C <sub>PD</sub> (1)	TC74ACT540		—	24	—	—	—	
		TC74ACT541		—	27	—	—	—	

Note (1) C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

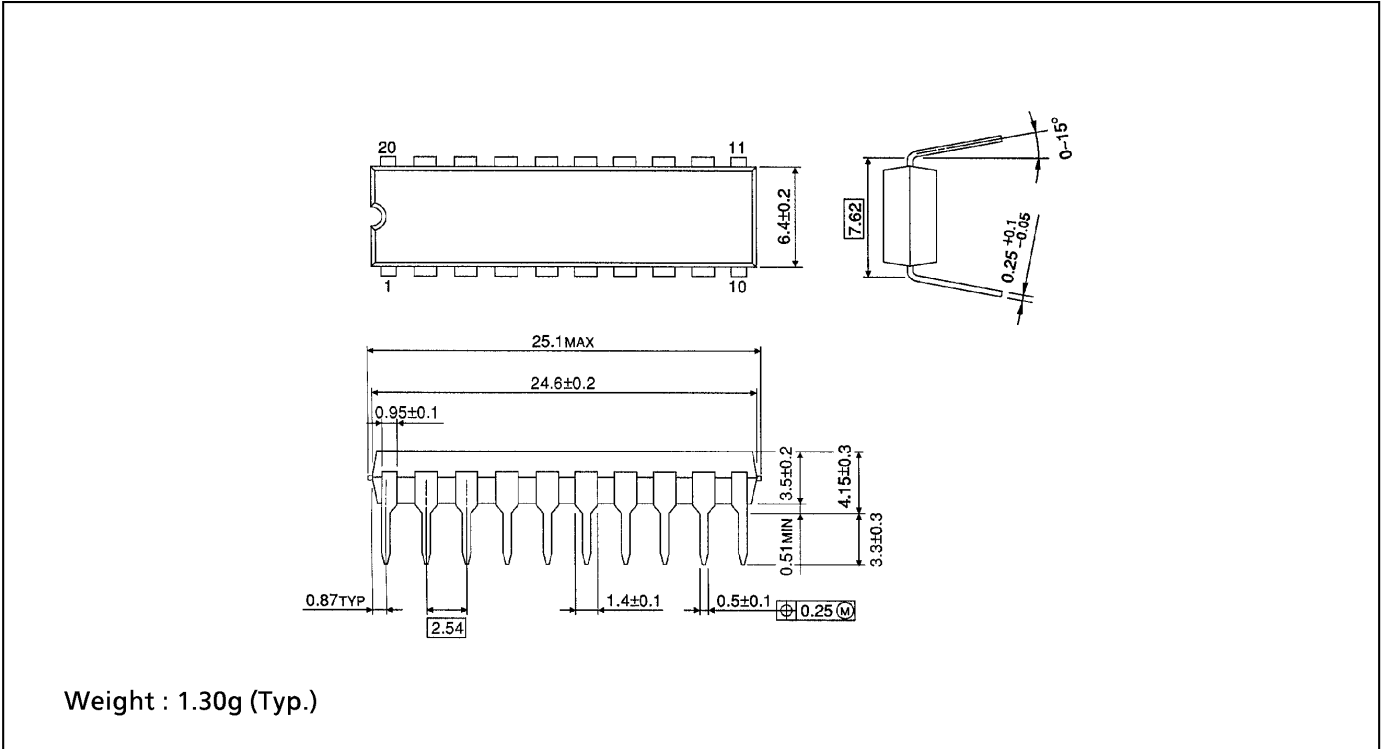
Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 8 (\text{per bit})$$

- (2) \* for TC74ACT540 only  
\*\* for TC74ACT541 only

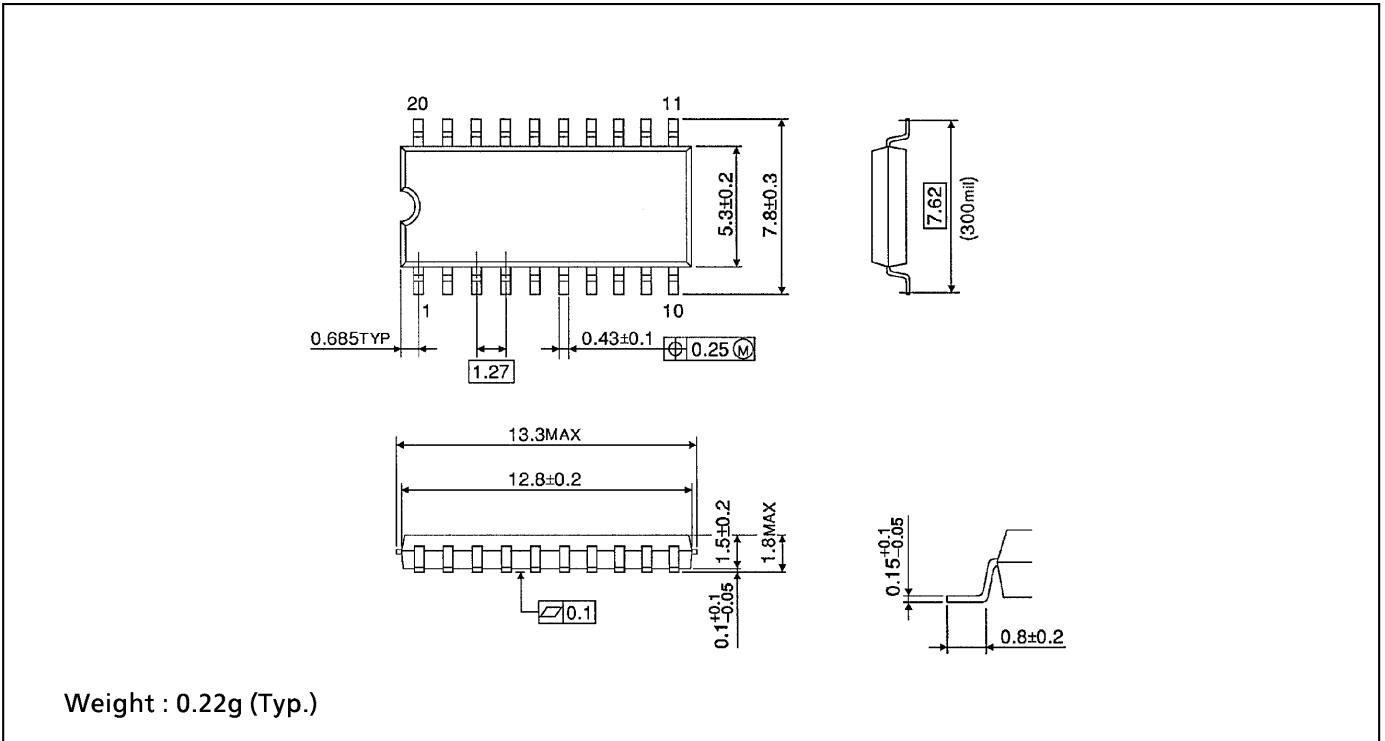
**DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)**

Unit in mm



**SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)**

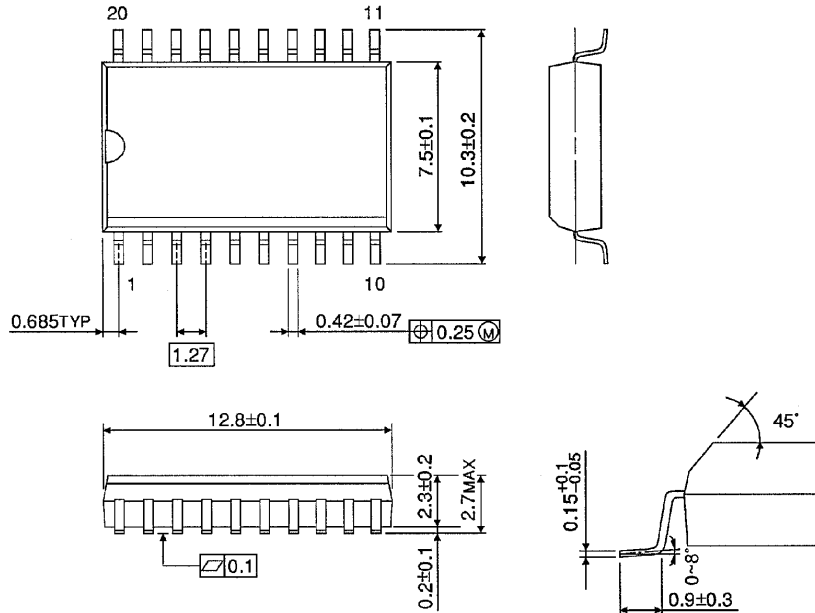
Unit in mm



**SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)**

Unit in mm

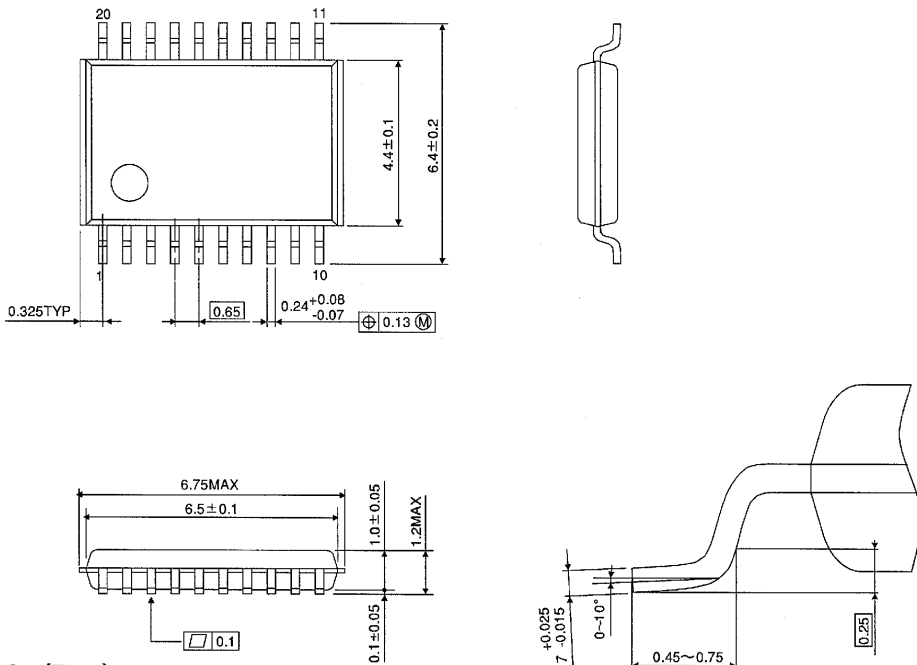
(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

**TSSOP 20PIN PACKAGE DIMENSIONS (TSSOP20-P-0044-0.65)**

Unit in mm



Weight : 0.08g (Typ.)

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